

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
EISEI IN	04/05/2021
KOHEI HIZONO	04/05/2021
RECEIVING PARTY DATA	
Name:	SAGINOMIYA SEISAKUSHO, INC.
Street Address:	55-5, WAKAMIYA 2-CHOME
Internal Address:	NAKANO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	1650033
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17295215
CORRESPONDENCE DATA	
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Address Line 4:	SALT LAKE CITY, UTAH 84111
ATTORNEY DOCKET NUMBER:	14321.300
NAME OF SUBMITTER:	DANA L. TANGREN
SIGNATURE:	/dana l. tangren/
DATE SIGNED:	05/19/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 3	
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COMBINED DECLARATION and ASSIGNMENT
(Utility, Design, National Stage of PCT)

TITLE OF INVENTION:² DYNAMIC CHARACTERISTIC MEASUREMENT DEVICE

As a below named inventor, I hereby declare that:

SPECIFICATION IDENTIFICATION

This declaration and assignment is directed to:

*(complete (a), (b), or (c))*³

- (a) ☐ The attached application (United States Application No. _____,
filed on _____);
- (b) ☐ Previously filed United States Application No. _____,
filed on _____; or
- (c) ☒ PCT International Application No. PCT/JP2019/035957, filed on September 12,
2019 (nationalized as United States Application No. 17/295251 filed on 05/19/2021)

I hereby authorize the patent attorneys and/or patent agents of Workman Nydegger to insert the
above Application No(s). and filing date(s) when known.

DECLARATION AND ACKNOWLEDGEMENT

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the
above-identified application.

I hereby state that I have reviewed and understand the contents of the above-identified
application, including the claim(s).

I acknowledge the duty to disclose all information which is material to patentability as defined in
37 C.F.R. § 1.56, including for continuation-in-part applications, material information which

became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT⁴

The Assignee, SAGINOMIYA SEISAKUSHO, INC., having a principal place of business at 55-5, Wakamiya 2-chome, Nakano-ku, Tokyo 1650033 Japan, desires to secure the entire right, title and interest in the above-identified application.

In consideration of One Dollar (\$1.00) and other good and valuable consideration paid to me by the Assignee, the receipt and sufficiency of which is hereby acknowledged, I HEREBY ASSIGN TO THE ASSIGNEE:

The entire right, title and interest in the above-identified application and in all divisions, continuations and continuations-in-part of said application and in all patents issuing thereon in the United States and in all reissues or extensions of patents granted thereon.

The right to claim priority to or the benefit of any prior related United States or foreign patent applications including under all applicable treaties and conventions.

I hereby authorize and request the United States Commissioner of Patents and Trademarks, to issue any and all patents on said application to the Assignee as the owner of the entire interest, for the sole use and behoof of the said Assignee, its successors, assigns and legal representatives.

I hereby agree, without further consideration, to sign all lawful papers and to perform all other lawful acts which the Assignee may request me to make this Assignment fully effective, including, by way of example but not of limitation, the following:

Prompt execution of all original, divisional, continuation, continuation-in-part, substitute, reissue, and other United States applications and all lawful documents requested by the Assignee to further the prosecution of any of such patent applications.

With regard to the above-identified application and applications claiming priority thereto, cooperate to the best of my ability in: (1) proceedings relating to

nullification, reissue, extension, post grant, inter parties, derivation, supplemental examination, and infringement; (2) execution of all lawful documents; and (3) the production of evidence.

This assignment and agreement shall be binding upon my heirs and legal representatives.

SIGNATURE(S)⁵

NOTE: Carefully indicate the family (or last) name, as it should appear on the filing receipt and all other documents.

Full name of sole or first inventor

	<u>Eisei</u> <small>(GIVEN NAME)</small>		<u>IN</u> <small>(MIDDLE INITIAL OR NAME)</small>		<u></u> <small>FAMILY (OR LAST NAME)</small>
Signature	<u>Eisei IN</u>	Date	<u>April 5, 2021</u>		
Residence	<u>Sayama-shi</u> <small>(city)</small>		<u>Japan</u> <small>(State or Country)</small>		
Mailing Address	<u>c/o SAGINOMIYA SEISAKUSHO, INC., Sayama Jigyosho, 535,</u> <u>Sasai, Sayama-shi, Saitama 3501395 Japan</u>				

Full name of second joint inventor, if any

	<u>Kohei</u> <small>(GIVEN NAME)</small>		<u></u> <small>(MIDDLE INITIAL OR NAME)</small>		<u>HIZONO</u> <small>FAMILY (OR LAST NAME)</small>
Signature	<u>kohei HIZONO</u>	Date	<u>April 5, 2021</u>		
Residence	<u>Sayama-shi</u> <small>(city)</small>		<u>Japan</u> <small>(State or Country)</small>		
Mailing Address	<u>c/o SAGINOMIYA SEISAKUSHO, INC., Sayama Jigyosho, 535,</u> <u>Sasai, Sayama-shi, Saitama 3501395 Japan</u>				

Full name of third joint inventor, if any

	<u></u> <small>(GIVEN NAME)</small>		<u></u> <small>(MIDDLE INITIAL OR NAME)</small>		<u></u> <small>FAMILY (OR LAST NAME)</small>
Signature	<u></u>	Date	<u></u>		
Residence	<u></u> <small>(city)</small>		<u></u> <small>(State or Country)</small>		
Mailing Address	<u></u>				

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